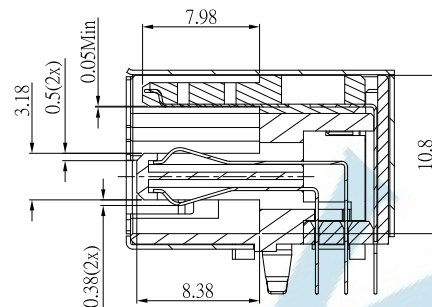
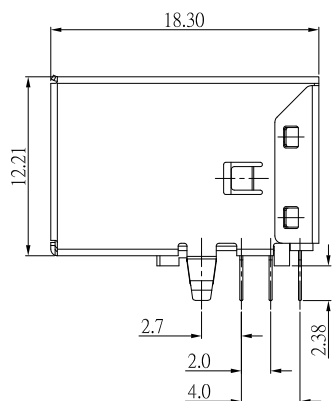


Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdB_SSTX-
6	StdB_SSTX+
7	GND_DRAIN
8	StdB_SSRX-
9	StdB_SSRX+
Shell	Shield

NOTE:

1.MATERIAL:

- 1.1 Housing: LCP,(UL94V-0)
- 1.2 Contact: 1-4 Pin: COPPER
- 5-9 Pin: BRASS

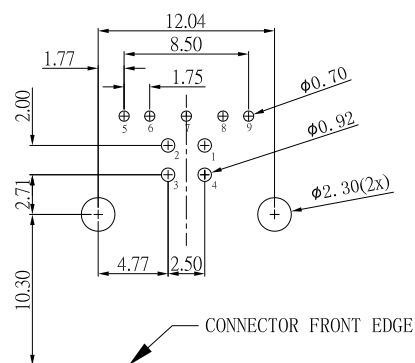
1.3 Shell: BRASS

2.Finish:

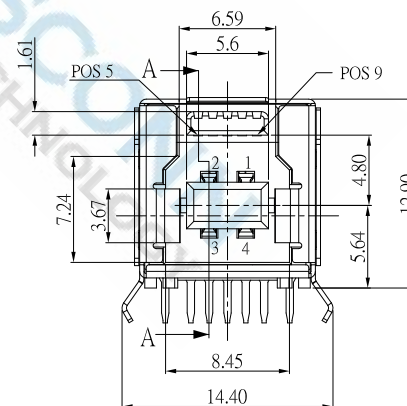
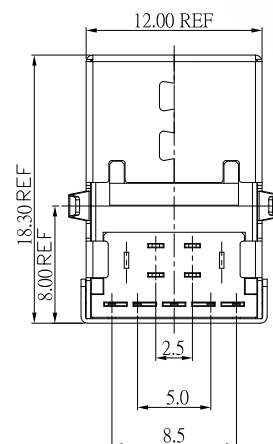
- 2.1 Contact: Plated Gold in Mating Area ;
- Tin Plated on Solder Balls ;
- Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate:1.5 Amp
- 3.2 insulator Resistance:1000M Ω Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30m Ω Max
- 3.5 Operation Temperature: -40°C ~ +85°C
- 3.6 Insertion Force: 3.57 Kg Max
- 3.7 Extraction Force: 1.02 Kg Min



RECOMMENDED PCB LAYOUT



DIMENSIONS TOLERANCE	單位(UNITS)	MM	處理(FINISH)	SEE NOTE	審校(CH'K)	Calvin	圖名(NAME)		WISCONN Technology Co.,Ltd Tel:02-2742-1798 Fax:02-2742-1898									
	METRIC						USB3.0 BF R/A 15u"											
	數量(QT'Y)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena	料號(PART NUMBER)										WU3BF-0915PBUDR	
	.0 $\pm$ 0.30 .00 $\pm$ 0.20 .000 $\pm$ 0.10 ANG.= $\pm$ 2°						圖號(DRAW NUMBER)		T002		比例 (SCALE)	1/1	圖紙 (SIZE)	A4	頁次 (SHEET)	1	版次 (REV.)	A
	材料(MT'L)	SEE NOTE	設計(DE'N)	Mike	日期(DATE)	OCT.15.2007	圖檔(FILE NAME .DWG)											